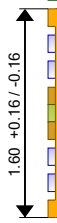


Layer	Stack up	Supplier	Supplier Description	Description	Type	Tg	εr	Base Thickness	Processed Thickness
	[1]								
1		Electra Polymers		Liquid PhotoImageable Mask	SolderMask			4.000	
		Circuitfoil		Copper Foil	Copper			0.018	0.036
2		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.069
		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.183
3		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.510	0.510
		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.183
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.069
4		Circuitfoil		Copper Foil	Copper			0.018	0.036
		Electra Polymers		Liquid PhotoImageable Mask	SolderMask			4.000	
	[4]								



Copper Thickness = 0.142 | Dielectric Thickness = 1.014 | Solder Mask Thickness = 0.050 | Stack Up Thickness = 1.156 | Stack Up Thickness with Soldermask = 1.206 | Stack Up Cost = 23.00 |

Notes

StackName: Mlb4_1.2mm_TraX	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1
Date: 11/2/2016	Associated Documents:					
Author: H. Ndala						
Department: CAM						
Site: Diep River						